

# **2019 18th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm 2019)**

**Las Vegas, Nevada, USA  
28-31 May 2019**

**Pages 1-683**



**IEEE Catalog Number: CFP19ITH-POD  
ISBN: 978-1-7281-2462-9**

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IEEE Catalog Number:	CFP19ITH-POD
ISBN (Print-On-Demand):	978-1-7281-2462-9
ISBN (Online):	978-1-7281-2461-2
ISSN:	1087-9870

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